

# 11<sup>th</sup> Gen Intel® Tiger Lake Embedded PC



## Features

- ✓ Intel® 11<sup>th</sup> Gen Tiger Lake-UP3 SoC processors(TDP 15W)
- ✓ 2 x DDR4 3200Mhz SO-DIMM, up to 64GB
- ✓ 1 x Intel i219-LM GbE, 1 x Intel i225-V 2.5GbE
- ✓ 1 x M.2 M-Key 2242/2280 support NVMe, 1 x M.2 E-key 2230 support CNVi, 1 x M.2 B-key 3042/3052
- ✓ 4 x 4K display via 2 x HDMI, 2 x DP 1.4 (from USB 3.2 Type-C)
- ✓ Support Fanless Cooling design, Wide voltage support
- ✓ Optional TPM 2.0 support



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## Specification

Processor System	CPU	Intel® Tiger Lake –UP3 i5-1145G7E processor (Default, TDP 15W) Intel® Tiger Lake-UP3 i5-1135G7 processor (TDP 15W)
	BIOS	AMI Flash ROM
Memory	Technology	2 x DDR4 3200 SO-DIMM Dual channel, max support 64GB
Storage	SATA	1 x 2.5" SATA III Device
	M.2	1 x M.2 M-key 2242/2280 (PCIe4.0 x 4/ SATA III) support NVMe
Network	LAN	1 x Intel i219-LM GbE 1 x Intel i225-V 2.5GbE
Graphics	Technology	Intel® HD Graphics, shared memory 2 x HDMI 2.0b (Max resolution: 4096x2160@60Hz) 2 x DP1.4 (Max resolution: 4096 x 2304@60Hz) from USB Type-C Support 4 x independent 4K HDR or 1 x 8K Display
Expansion	M.2	1 x M.2 E-key 2230 (USB 2.0/PCIex1 ) support CNVi 1 x M.2 B-key 3042/3052 (USB3.1/USB2.0/PCIex1)
Rear Panel I/O	USB 3.2	x 2 (Type C, support DP 1.4)
	SIM Card Slot	x 1
	HDMI	x 2
	RJ45	x 2
	DC Jack	x 1
Front Panel I/O	Audio	x 1 Audio Jack (Line out + MIC)
	USB 3.2	x 2 Type A, x 1 Type C
Internal I/O	Connectors/headers	N/A
Environment	Operating temperature	-10°C to 50°C (14 F to 122 F)
	Storage temperature	-20°C to 60°C (-4 F to 140 F)
Operating System	OS Support	Windows 10 , Linux
Dimension	Hardware	150(W) x 109(D) x 75(H) mm
Power	Power adaptor	DC 12V/7.5A 90W, M/B input: 12 ~ 24V input